



Material Content Data Sheet



Sales Product Name		BTS5210L		Issued		29. August 2013			
MA#		MA001114876							
Package		PG-DSO-12-9		Weight*		366.64 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	3.505	0.96	0.96	9559	9559	
leadframe	non noble metal	iron	7439-89-6	0.204	0.06		557		
	inorganic material	phosphorus	7723-14-0	0.061	0.02		167		
	non noble metal	copper	7440-50-8	203.829	55.58	55.66	555937	556661	
wire	non noble metal	aluminium	7429-90-5	0.704	0.19	0.19	1920	1920	
encapsulation	organic material	carbon black	1333-86-4	0.303	0.08		825		
	plastics	epoxy resin	-	21.633	5.90		59003		
	inorganic material	silicondioxide	60676-86-0	129.345	35.28	41.26	352783	412611	
leadfinish	non noble metal	tin	7440-31-5	3.310	0.90	0.90	9027	9027	
plating	inorganic material	phosphorus	7723-14-0	0.001	0.00		4		
	non noble metal	nickel	7440-02-0	0.617	0.17	0.17	1684	1688	
solder	noble metal	silver	7440-22-4	0.078	0.02		213		
	non noble metal	tin	7440-31-5	0.063	0.02		171		
	non noble metal	lead	7439-92-1	2.988	0.82	0.86	8150	8534	
*deviation	< 10%					Sum in total:	100.00		1000000

Important Remarks:

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